

Image

S/N: 09/832,884

2/26/2004

DOCKET NO.: L/M-102-DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: 09/832,884
Divisional of 09/321,565

Confirmation No.: 2718

Applicant: Steve M. Danziger, et al.

Art Unit: 2829

Filed: April 12, 2001

Examiner: Evan T. Pert

Docket No: L/M-102-DIV

Customer No: 28892

For: Method and Apparatus for Evaluating a Known Good Die Using
Both Wire Bond and Flip-Chip Interconnects

TRANSMITTAL

US Patent & Trademark Office
2011 South Clark Place
Customer Window, Mail Stop: Non Fee Amendment
Crystal Plaza Two, Lobby, Room 1B03
Arlington, VA 22202

Sir: TRANSMITTED HERewith IS

☐ A RESPONSE, ☒ AN AMENDMENT, ☐ AN AMENDMENT AFTER FINAL,

IN THE ABOVE-IDENTIFIED APPLICATION.

☐ Small entity status of this application under 37 CFR §1.9(f) is established
by a verified statement under 37 CFR §1.27

☐ previously submitted.

☐ submitted herewith.

☒ No additional fee is required, as shown below.

CLAIMS PENDING AFTER AMENDMENT		CLAIMS PREVIOUSLY PAID		NEW CLAIMS EXTRA		ADDITIONAL FEES			
						SMALL ENTITY		OTHER THAN SMALL ENTITY	
TOTAL	5	MINUS	20	=	0	x\$9=	0.00	x\$18=	0.00
INDEP	1	MINUS	3	=	0	x43=	0.00	x\$86=	0.00
NEW MULTIPLE DEPENDENT CLAIMS					0	x\$145=	0.00	x\$290=	0.00
AND CLAIMS DEPENDENT THEREON					0	x\$145=	0.00	x\$290=	0.00
TOTAL ADDITIONAL FEE						0.00		0.00	

☒ X

This amount is believed to be correct, however, the Commissioner is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account No. 19-2816. This authorization applies to both filing fees under 37 CFR §1.16 and processing fees (such as extension of time) under 37 CFR §1.17. A duplicate copy of this transmittal is attached.

Respectfully Submitted,



Ronald R. Snider
Registration No. 24,962

Date: February 26, 2004

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AMENDMENT

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Sir:

In response to the Office Action of February 10, 2004, please
amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of
claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.